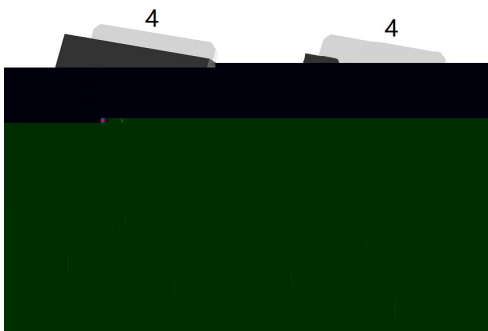
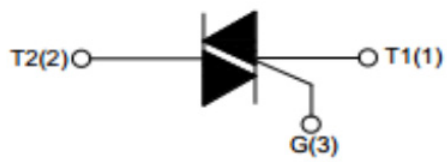


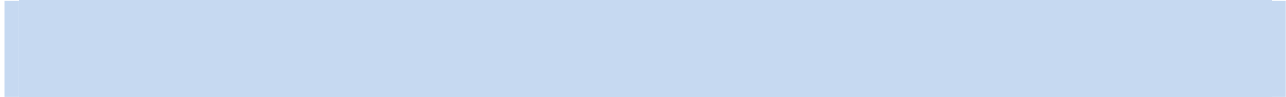
TO-252



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		~	℃
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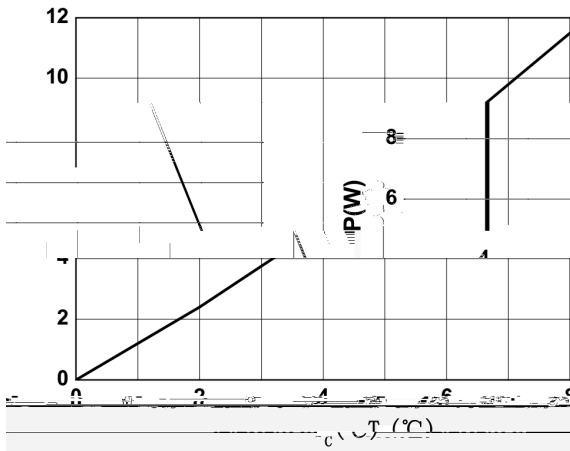


FIG.2: RMS on-state current versus case temperature

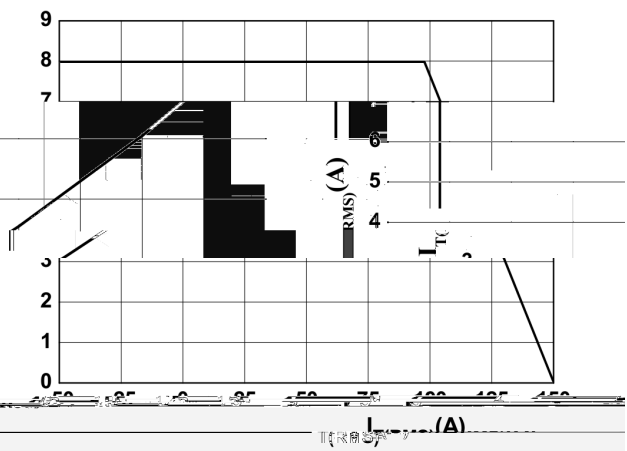


FIG.1 Maximum power dissipation versus RMS on-state current

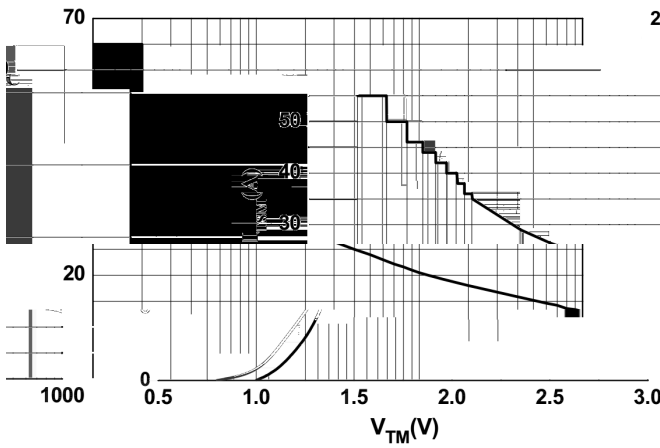


FIG.4: On-state characteristics

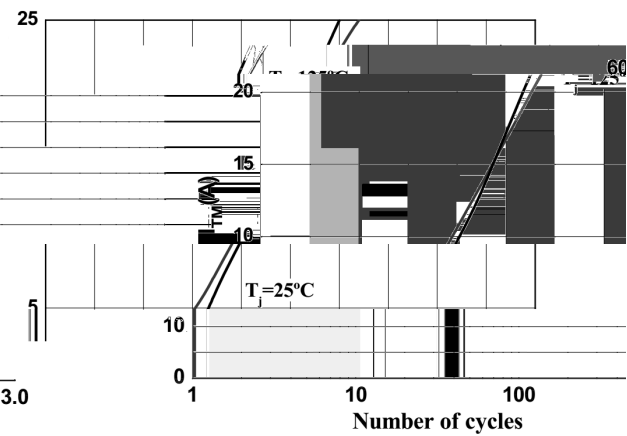


FIG.3: Surge peak on-state current versus number of cycles

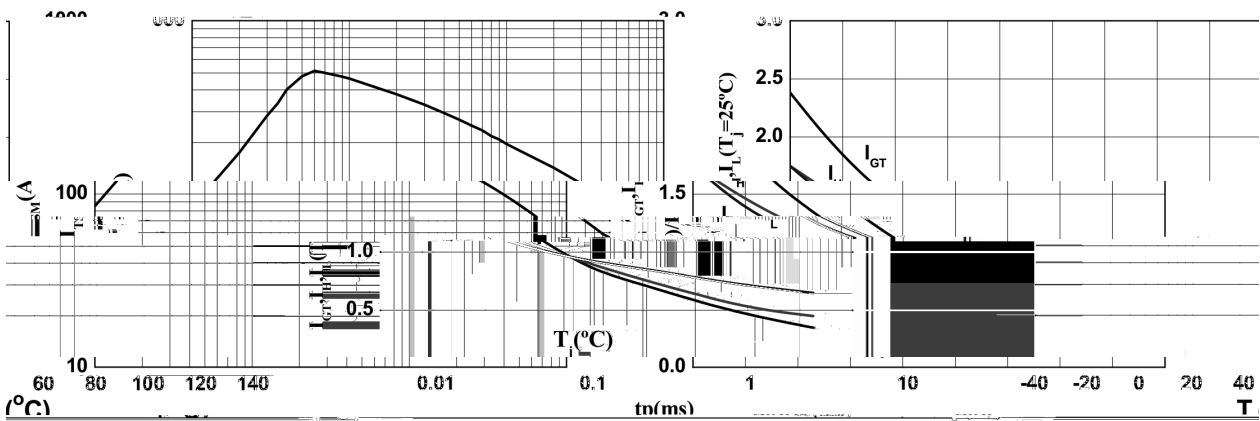


FIG.6: Relative variations of gate trigger

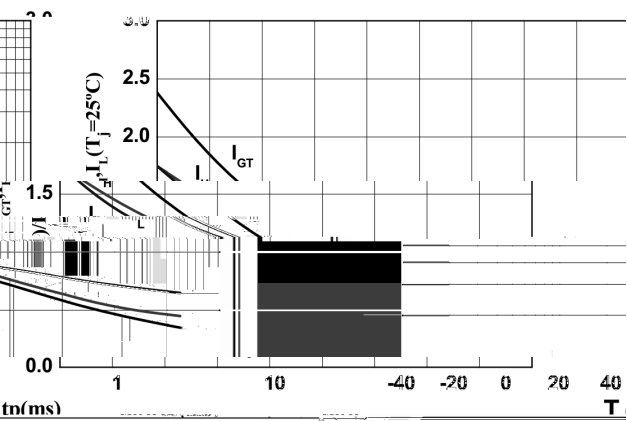
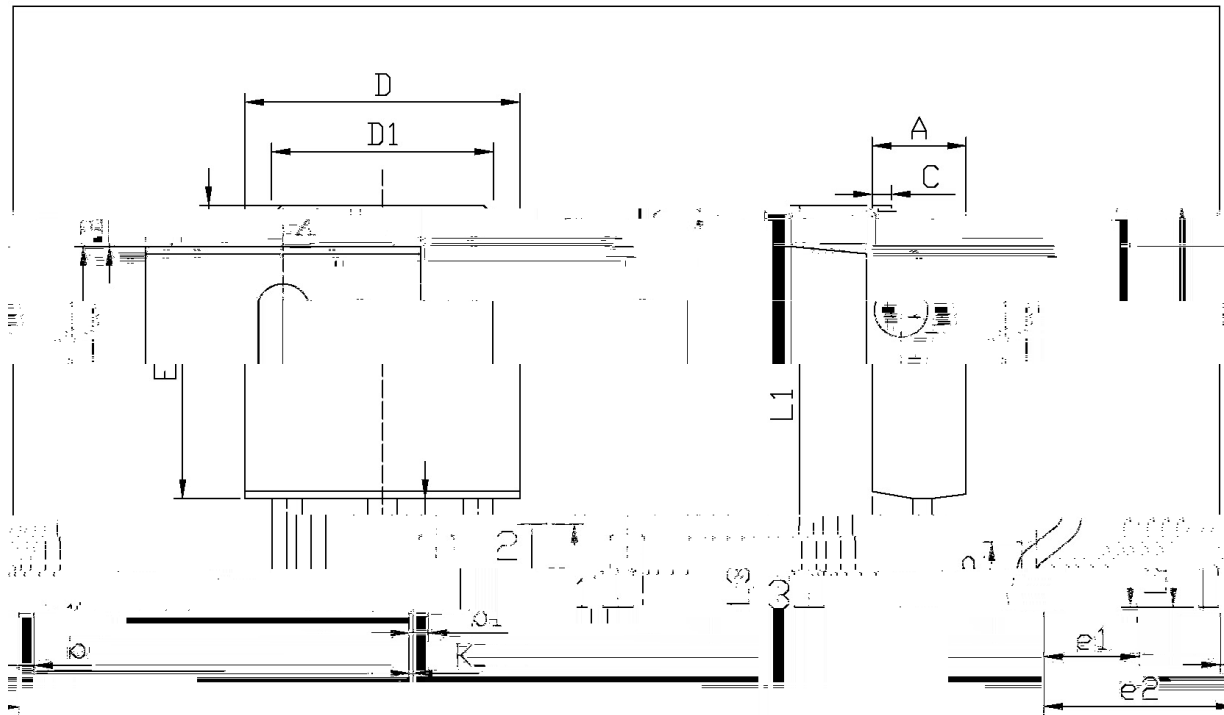


FIG.5: Non-repetitive surge peak on-state current



单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.50	0.90	e2	4.43	4.73
b1	0.45	0.55	L1	9.45	9.95
C	0.45	0.55	L2	1.25	1.75
D	6.45	6.75	L3	0.60	0.90
D1	5.10	5.50	K	0.00	0.10

TO-252

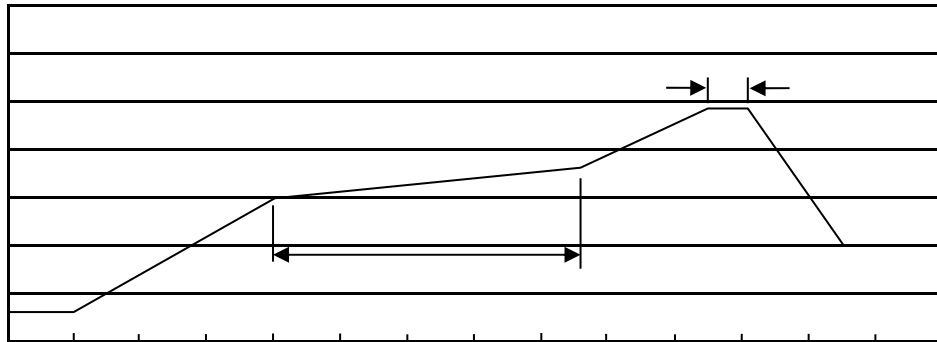
BR

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I_{GT}

Temperature Profile for IR Reflow Soldering(Pb-Free)



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